

METHOD OF INCREASING THE AREA OF A USEFUL LAYER OF MATERIAL TRANSFERRED ONTO A SUPPORT

ABSTRACT

5 The invention relates to a method of increasing the area of a useful layer of
material coming from a source substrate and which is effectively transferred onto a support
substrate. The dimensions of the outer outline of one of the source and support substrates,
referred to as the "first" substrate, are greater than the dimensions of the outer outline of the
other substrate, referred to as the "second" substrate. The outer outline of the flat central zone of
10 the first substrate presents dimensions greater than the dimensions of the outer outline of the flat
central zone of the second substrate. During bonding, the substrates are applied one against the
other in such a manner that the outline of the flat central zone of the second substrate is disposed
within the outline of the flat central zone of the first substrate. The invention is applicable, for
example, to fabricating a composite substrate product wafer for use in the fields of electronics,
15 optics, or optoelectronics.